imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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BR Series Bare Element Current Sense Resistor

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Resistive Product Solutions

Features:

- 1, 3 and 5 watts
- \pm 1%, \pm 2% or \pm 5% tolerance
- ±20 ppm/⁰C element wire
- ±200 ppm/^oC at lead stops
- All welded construction
- Flameproof
- Non-inductive (10nH max)
- High current handling to 70 amps
- RoHS compliant / lead-free

Applications:

- Feedback
- Low inductance
- Surge and pulse

Current sensing

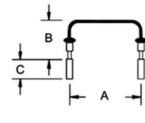
Electrical Specifications					
Turne / Oa da	Power Rating (Watts)	Ohmic Range (Ω) and Tolerance ⁽¹⁾			
Type / Code	at 85⁰C	1%, 2%, 5%			
BR1	1W	0.005 - 0.1			
BR3	3W				
BR5	5W	0.005 - 0.05			

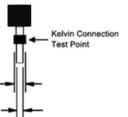
(1) Contact factory for resistance values below 0.005Ω .

Product photo shown above is typical. Actual components may vary depending on element wire size and amount of trim adjusting required to meet desired resistance value.

Please refer to the High Power Resistor Application Note (page 3) for more information on designing and implementing high power resistor types.

Mechanical Specifications





Element width varies depending on resistance value.

Type / Code	А	В	С	D	E	Unit
BR1	0.450 + 0.040 / -0.020 11.43 + 1.02 / -0.51			0.065 + 0.010 / - 0.005 1.65 + 0.25 / - 0.13		
BR3				0.065 + 0.010 / - 0.005 1.65 + 0.25 / - 0.13		
BR5				0.065 + 0.010 / - 0.005 1.65 + 0.25 / - 0.13		inches mm



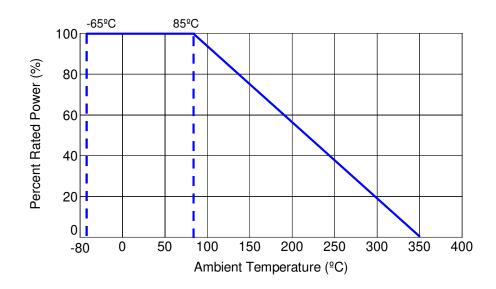
BR Series Bare Element Current Sense Resistor

Power Derating Curve:

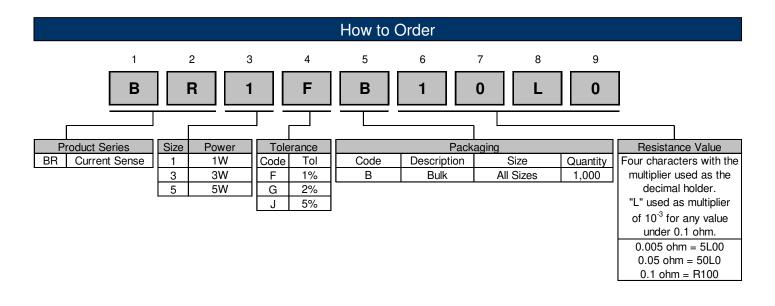
Stackpole Electronics, Inc. Resistive Product Solutions

Product Solutions

Performance Characteristics				
Test	Test Results			
Moisture Resistance	±1%			
Load Life @ 25ºC - 1,000 hrs.	±2%, + 0.0005Ω			
Temperature Cycle @ -40°C & +125°C (1,000 cyc)	±1%			



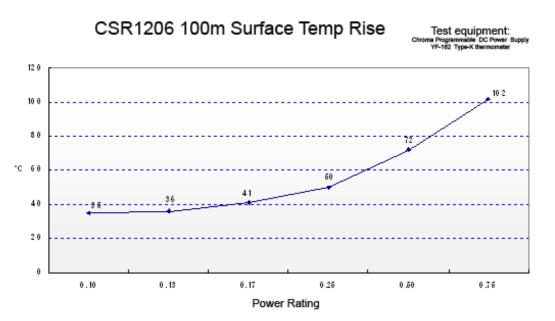
Note: Maximum recommended solder joint/lead stop temperature = +105°C



High Power Chip Resistors and Thermal Management

Stackpole has developed several surface mount resistor series in addition to our current sense resistors, which have had higher power ratings than standard resistor chips. This has caused some uncertainty and even confusion by users as to how to reliably use these resistors at the higher power ratings in their designs.

The data sheets for the RHC, RMCP, RNCP, CSR, CSRN, CSRF, CSS, and CSSH state that the rated power assumes an ambient temperature of no more than 100 degrees C for the CSS / CSSH series and 70 degrees C for all other high power resistor series. In addition, IPC and UL best practices dictate that the combined temperature on any resistor due to power dissipated and ambient air shall be no more than 105C. At first glance this wouldn't seem too difficult, however the graph below shows typical heat rise for the CSR 1/2 100 milliohm at full rated power. The heat rise for the RMCP and RNCP would be similar. The RHC with its unique materials, design, and processes would have less heat rise and therefore would be easier to implement for any given customer.



The 102 degrees C heat rise shown here would indicate there will be additional thermal reduction techniques needed to keep this part under 105C total hot spot temperature if this part is to be used at 0.75 watts of power. However, this same part at the usual power rating for this size would have a heat rise of around 72 degrees C. This additional heat rise may be dealt with using wider conductor traces, larger solder pads and land patterns under the solder mask, heavier copper in the conductors, vias through PCB, air movement, and heat sinks, among many other techniques. Because of the variety of methods customers can use to lower the effective heat rise of the circuit, resistor manufacturers simply specify power ratings with the limitations on ambient air temperature and total hot spot temperatures and leave the details of how to best accomplish this to the design engineers. Design guidelines for products in various market segments can vary widely so it would be unnecessarily constraining for a resistor manufacturer to recommend the use of any of these methods over another.

Note: The final resistance value can be affected by the board layout and assembly process, especially the size of the mounting pads and the amount of solder used. This is especially notable for resistance values $\leq 50 \text{ m}\Omega$. This should be taken into account when designing.